



Final Product Change Notification

201410013F01

Issue Date: 07-Apr-2015

Effective Date: 20-Jul-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online



QUALITY

Management Summary

Final notification about the release of additional PIN diodes at wafer fab DHAM (Hamburg, Germany)

Change Category

- | | | | |
|--------------------------------------------------------|---------------------------------------------|---------------------------------------------------------|----------------------------------------------------|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input checked="" type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Release of PIN diodes at NXP waferfab DHAM (Hamburg, Germany)

Details of this Change

Release of additional PIN diode types at NXP wafer fab location DHAM (Hamburg, Germany).

The wafer fab process for PIN diodes at NXP manufacturing location DHAM (Hamburg, Germany) including an initial group of PIN diode types has been released per January 1st 2014.

(The PIN diode process in ICN4, Nijmegen, The Netherlands, has been discontinued per 31-12-2013).

With this PCN additional PIN diode types have been released at NXP wafer manufacturing location DHAM, Hamburg, Germany. Find the results of the self-qualification plan attached to this PCN.

With the transfer to DHAM, there will be no change in type numbers, 12NC's, marking codes and datasheet for the concerned products with respect to the ICN4 products.

Customer products are attached to this FPCN.

For your information, the additional attached product type list includes all products from this FPCN.

For reasons of smooth transition there is no change in 12NC or marking on the devices but assembly fab and date code on packing and reel allow for full trace back to wafer fab details.

Why do we Implement this Change

In line with NXP manufacturing strategy

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 30-Mar-2015

Production

Planned first shipment 15-Jul-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 07-May-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name quality helpdesk BL RFSS
Position Quality engineer & Customer support
e-mail address bl.hprf.quality.helpdesk@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP | Privacy Policy | Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Customer Part#	Changed Part 12NC	Changed Part Description	Package Outline	Package Name	Status
BAP64Q,125	934064656125	Quad pin diode	SOT753	SO5	RFS
BAP65-03,115	934056547115	PIN DIODE	SOD323	SOD2	RFS
BAP65-02,115	934056546115	PIN DIODE	SOD523	SC-79	RFS
BAP64-04W,115	934056233115	PIN DIODE	SOT323	SC-70	RFS
BA891,115	934055282115	BANDSWITCH DIODES	SOD523	SC-79	RFS
BA591,115	934055230115	BANDSWITCH DIODES	SOD323	SOD2	RFS
BAP64Q,125	934064656125	Quad pin diode	SOT753	SO5	RFS
BAP65-02,115	934056546115	PIN DIODE	SOD523	SC-79	RFS
BAP64-04W,115	934056233115	PIN DIODE	SOT323	SC-70	RFS
BA891,115	934055282115	BANDSWITCH DIODES	SOD523	SC-79	RFS